



60V N-CHANNEL ENHANCEMENT MODE MOSFET H-BRIDGE

Product Summary

BV _{DSS}	R _{DS(ON)}	I _D T _A = +25°C
60V	$22m\Omega$ @ V _{GS} = 10V	10.6A
	$30m\Omega @ V_{GS} = 4.5V$	8.7A

Features

- Thermally Efficient Package Cooler Running Applications
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description

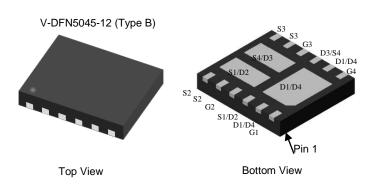
This new generation complementary MOSFET H-Bridge features low on-resistance achievable with low gate drive.

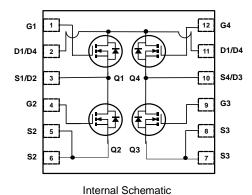
Applications

- Motor Control
- DC-DC Converters
- Power Management

Mechanical Data

- Case: V-DFN5045-12 (Type B)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.097 grams (Approximate)





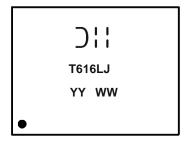
Ordering Information (Note 4)

Part Number	Case	Packaging
DMHT6016LFJ-13	V-DFN5045-12 (Type B)	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Dili=Manufacturer's Marking
T616LJ = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 16 = 2016)
WW = Week Code (01 to 53)



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			V_{DSS}	60	V
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Dunin Courset (Alata C) V 40V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	10.6 8.5	А
Continuous Drain Current (Note 6) V _{GS} = 10V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	Ι _D	14.8 11.9	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	60	Α		
Maximum Continuous Body Diode Forward Current (Note 6)			I _S	2	Α
Avalanche Current (Note 7) L=0.1mH			I _{AS}	15.3	Α
Avalanche Energy (Note 7) L=0.1mH			E _{AS}	11.7	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		P_{D}	1.16	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State		108	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	56	C/VV
Total Power Dissipation (Note 6)		P_{D}	2.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	В	46	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	24	
Thermal Resistance, Junction to Case (Note 6)		R ₀ JC	4.4	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

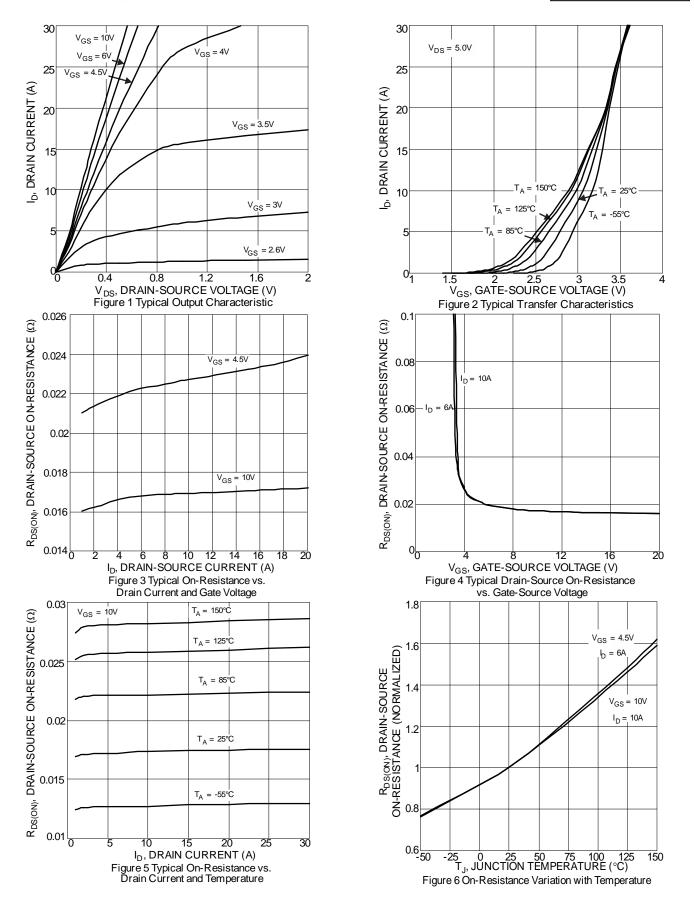
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	V _{DS} = 48V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	1	_	3	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance		_	17	22	mΩ	$V_{GS} = 10V, I_D = 10A$	
Static Diani-Source On-Resistance	R _{DS(ON)}	_	22.2	30	11177	$V_{GS} = 4.5V, I_D = 6A$	
Diode Forward Voltage	V_{SD}	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{ISS}	_	864	_		$V_{DS} = 30V$, $V_{GS} = 0V$, $f = 1MHz$	
Output Capacitance	Coss	_	282	_	pF		
Reverse Transfer Capacitance	C_{RSS}	_	27	_			
Gate Resistance	R _G	_	1.3	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_G	_	8.4	_			
Total Gate Charge (V _{GS} = 10V)	Q_{G}	_	17	_	nC Vps = 30V, lp = 10A		
Gate-Source Charge	Q _{GS}	_	3.1	_	IIC	$V_{DS} = 30V, I_{D} = 10A$	
Gate-Drain Charge	Q_{GD}	_	4.3	_			
Turn-On Delay Time	t _{D(ON)}	_	3.4	_			
Turn-On Rise Time	t _R	_	5.2	_		$V_{GS} = 10V, V_{DS} = 30V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	13	_	ns	$R_G = 6\Omega$, $I_D = 10A$	
Turn-Off Fall Time	t _F	_	7	_			
Reverse Recovery Time	t _{RR}	_	22	_	ns	1 400 41/44 4000/	
Reverse Recovery Charge	Q _{RR}	_	11	_	nC	$I_F = 10A$, di/dt = 100A/ μ s	

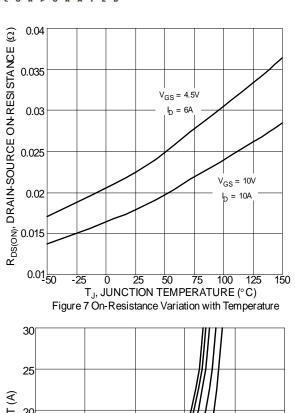
Notes:

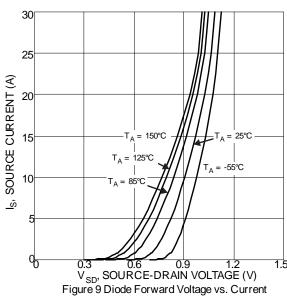
- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
- 7. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
 8. Short duration pulse test used to minimize self-heating effect.
 9. Guaranteed by design. Not subject to product testing.

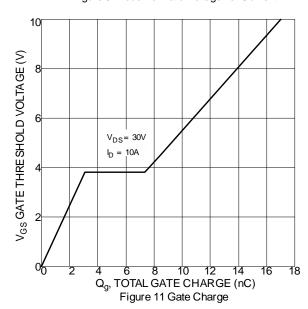












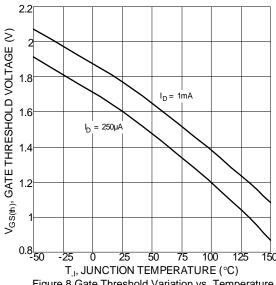
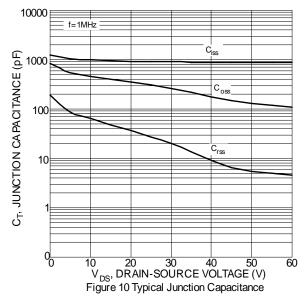
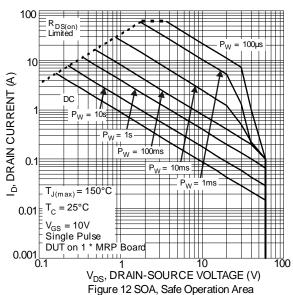
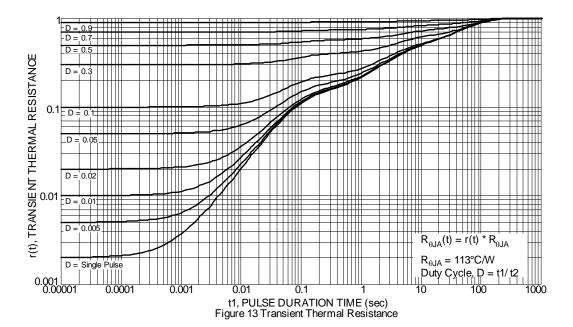


Figure 8 Gate Threshold Variation vs. Temperature







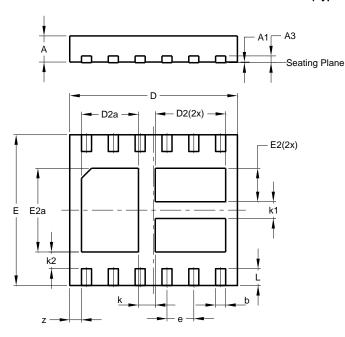




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

V-DFN5045-12 (Type B)

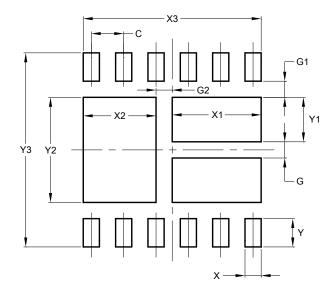


V-DFN5045-12							
	(Type B)						
Dim	Min	Тур					
Α	0.75	0.85	0.80				
A1	0.00	0.05	0.02				
A3	-	_	0.203				
b	0.25	0.35	0.30				
D	4.95	5.05	5.00				
D2	2.00	2.20	2.10				
D2a	1.60	1.80	1.70				
Е	4.45	4.55	4.50				
E2	E2 0.90		1.00				
E2a	E2a 2.40		2.50				
е	_	_	0.80				
k	_	_	0.50				
k1	C		0.50				
k2	_	_	0.50				
L	0.45	0.55	0.50				
Z	_	_	0.35				
All	All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

V-DFN5045-12 (Type B)



Dimensions	Value (in mm)
С	0.800
G	0.40
G1	0.40
G2	0.40
Х	0.40
X1	2.20
X2	1.80
Х3	4.40
Y	0.700
Y1	1.100
Y2	2.600
Y3	4.800



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